

WLCSP5_2-1-2

wafer level chip-size package; 5 bumps (2-1-2); 0.4 mm pitch;
0.77 x 1.17 x 0.57 mm body

7 June 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP5
Package style descriptive code	UC (uncased chip)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	11-2-2010
Manufacturer package code	WLCSP5

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.72	-	0.77	0.82	mm
E	package width	1.12	-	1.17	1.22	mm
A	seated height	0.54	-	0.57	0.6	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	5	-	

2. Package outline

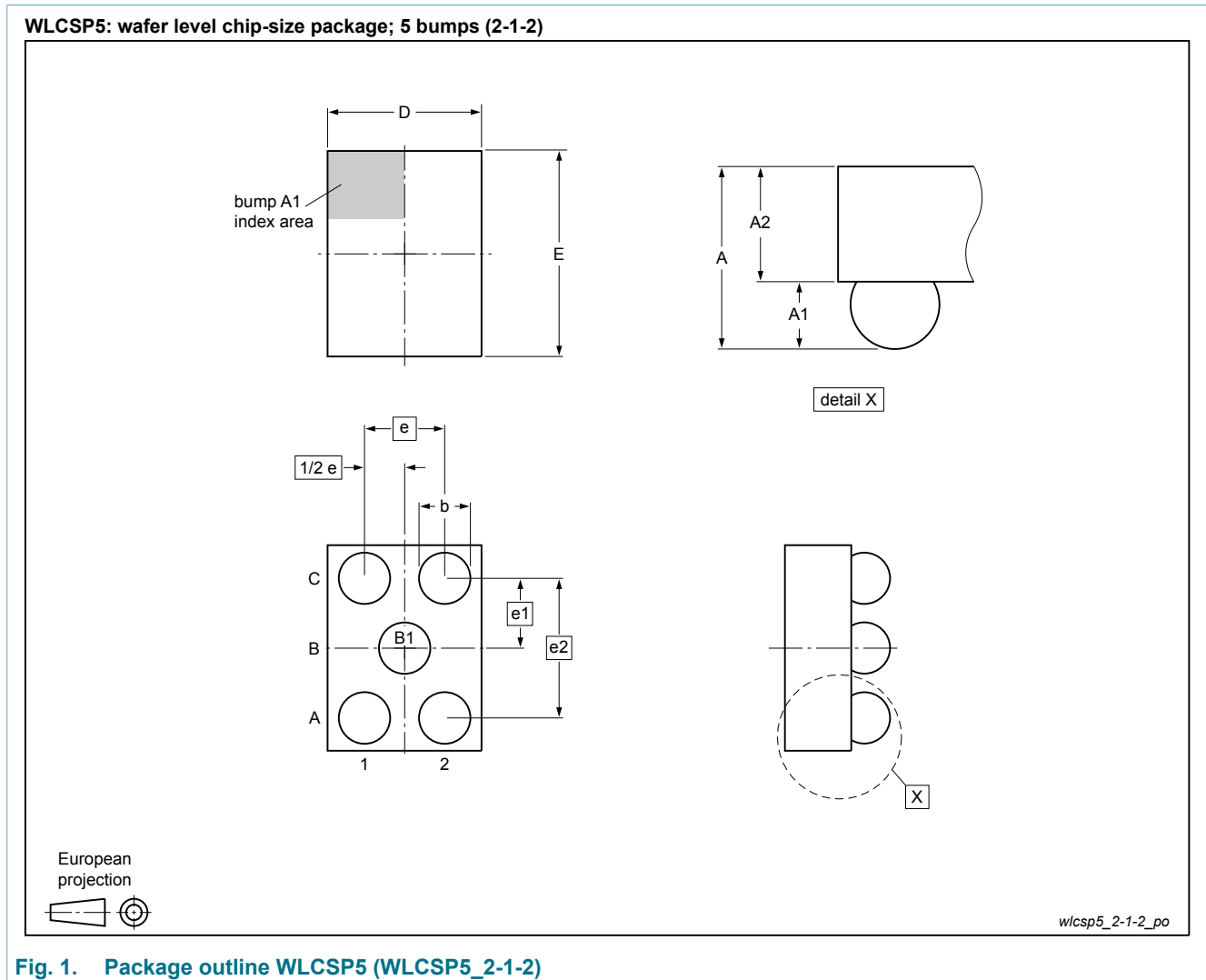


Fig. 1. Package outline WLCSP5 (WLCSP5_2-1-2)

3. Legal information

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